

N-Channel Enhancement Mode MOSFET

Description

The NTD3055L104T4G uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

TO-252-2L (TO-252-2(DPAK))

General Features

 $V_{DS} = 60V I_{D} = 20 A$

 $R_{DS(ON)}$ < 32m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply

PIN2 D PIN1 G PIN3 S

N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
NTD3055L104T4G	TO-252-2L(TO-252-2(DPAK))	HXY MOSFET	2500

Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	rain-Source Voltage 60	
Vgs	Gate-Source Voltage	±20	V
In@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	20	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	10	А
Ірм	Pulsed Drain Current ²	80	А
EAS	Single Pulse Avalanche Energy ³	38	mJ
P _D @T _C =25°C	Total Power Dissipation⁴	34.7	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	Operating Junction Temperature Range -55 to 150	



Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics				•				
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60	-	-	V	
Gate-Body Leakage Current		Igss	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain Current	T _J =25°C		.,	-	-	1		
	T _J =100°C	IDSS	I_{DSS} $V_{DS} = 60V$, $V_{GS} = 0V$		-	100	μA	
Gate-Threshold Voltage		V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2	1.7	2.5	V	
			V _{GS} = 10V, I _D = 10A	-	25	32	0	
Drain-Source on-Resistance	,	R _{DS(on)}	V _{GS} = 4.5V, I _D = 5A	-	31.5	40	mΩ	
Forward Transconductance ⁴		g fs	V _{DS} = 5V, I _D = 10A	-	15.5	-	S	
Dynamic Characteristic	s ⁵							
Input Capacitance		Ciss		-	1355	-		
Output Capacitance		Coss	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz	-	60	-	pF	
Reverse Transfer Capacitance		Crss	_	-	49	-		
Gate Resistance		Rg	f=1MHz	-	1.2	-	Ω	
Switching Characteristi	CS ⁵							
Total Gate Charge		Qg		-	22	-	nC	
Gate-Source Charge		Q _{gs}	$V_{GS} = 10V, V_{DD} = 30V,$ $I_{D} = 10A$	-	4.2	-		
Gate-Drain Charge		Q_{gd}		-	6.9	-		
Turn-on Delay Time		t _{d(on)}		-	6.4	-		
Rise Time		t _r	V _{GS} =10V, V _{DD} = 30V,	-	15.3	-	no	
Turn-off Delay Time		t _{d(off)}	$R_G = 3\Omega$, $I_D = 10A$	-	25	-	ns	
Fall Time		t _f		-	7.6	-		
Body Diode Reverse Recovery Time		trr		-	26	-	ns	
Body Diode Reverse Recovery Charge		Qrr	- I _F =10A, dI _F /dt=100A/μs	-	45	-	nC	
Drain-Source Body Diode Characteristics								
Diode Forward Voltage ⁴		V _{SD}	I _S = 10A, V _{GS} = 0V	-	-	1.2	V	
Continuous Source Current	T _C =25°C	Is	-	-	-	20	Α	

Notes:

- 1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C
- 2. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.4mH, I_{AS} =14A
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. This value is guaranteed by design hence it is not included in the production test.



Typical Characteristics

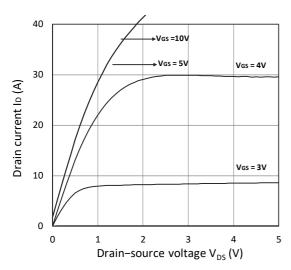


Figure 1. Output Characteristics

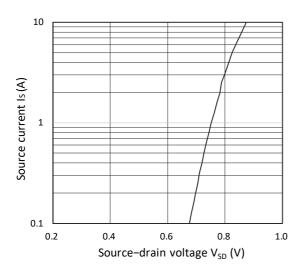


Figure 3. Forward Characteristics of Reverse

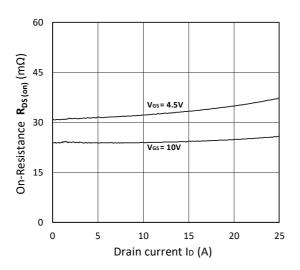


Figure 5. $R_{DS(ON)}$ vs. I_D

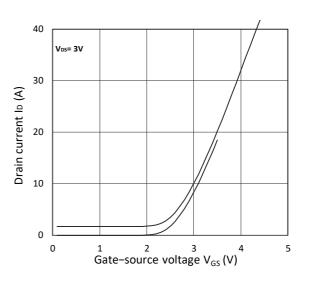


Figure 2. Transfer Characteristics

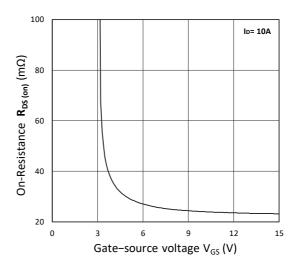


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

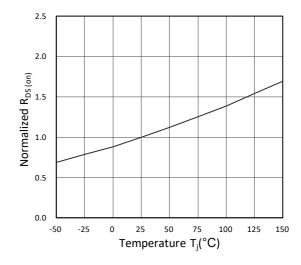
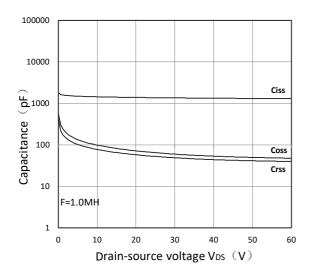


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

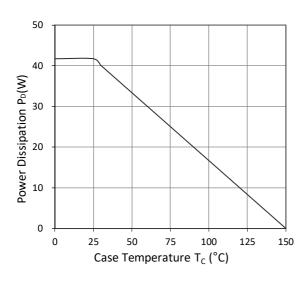




Vos = 30V | 10= 10A | 2 | 2 | 25 | Qg-Toal Gate Charge (nC)

Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics



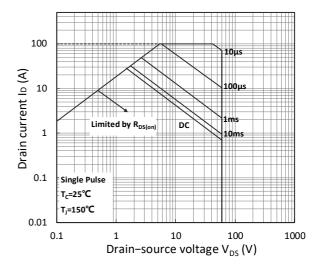


Figure 9. Power Dissipation

Figure 10. Safe Operating Area

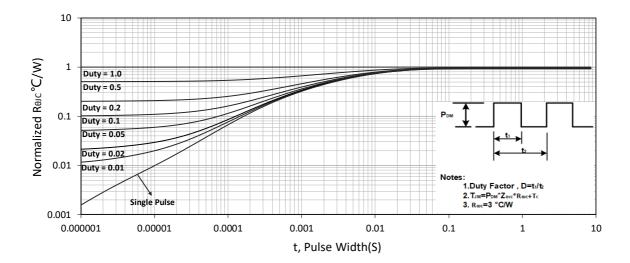
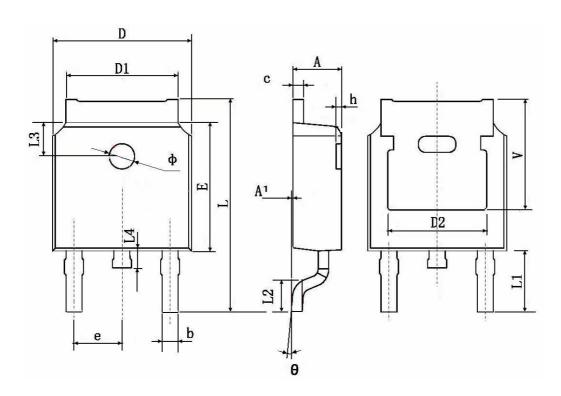


Figure 11. Normalized Maximum Transient Thermal Impedance

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TO-252-2L(TO-252-2(DPAK)) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
Α	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
С	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483	0.483 TYP.		TYP.
Е	6.000	6.200	0.236	0.244
е	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Ф	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	



P-Channel Enhancement Mode MOSFET

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